

CELCON®

Celcon® acetal copolymer grade M15HP is a creep resistant, high viscosity polymer providing optimum performance in injection molding. This grade provides overall excellent performance in applications requiring high stiffness. Chemical abbreviation according to ISO 1043-1: POM

Product information			
Resin Identification	POM		ISO 1043
Part Marking Code	>POM<		ISO 11469
-			
Rheological properties			
Melt volume-flow rate	1.3	cm ³ /10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	
Moulding shrinkage, parallel	2.3	%	ISO 294-4, 2577
Moulding shrinkage, normal	1.9	%	ISO 294-4, 2577
Typical mechanical properties			
Tensile modulus	2800	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min		MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	16		ISO 527-1/-2
Flexural modulus	2750		ISO 178
Compressive stress at 1% strain		MPa	ISO 604
Charpy impact strength, 23°C	280	kJ/m²	ISO 179/1eU
Charpy impact strength, -30°C	220	kJ/m²	ISO 179/1eU
Charpy notched impact strength, 23°C	11	kJ/m²	ISO 179/1eA
Charpy notched impact strength, -30°C	8.5	kJ/m²	ISO 179/1eA
Izod notched impact strength, 23°C	9.5	kJ/m²	ISO 180/1A
Hardness, Rockwell, M-scale	84		ISO 2039-2
Poisson's ratio	0.401		
Thermal properties			
Melting temperature, 10°C/min	173	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	101		ISO 75-1/-2
Temperature of deflection under load, 0.45 MPa	158		ISO 75-1/-2
Vicat softening temperature, 50°C/h 10N	167		ISO 306
Coefficient of linear thermal expansion	110	E-6/K	ISO 11359-1/-2
(CLTE), parallel			
Coefficient of linear thermal expansion (CLTE),	120	E-6/K	ISO 11359-1/-2
normal			
Physical/Other properties			
Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	0.75	%	Sim. to ISO 62
Density	1410	kg/m³	ISO 1183



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Injection

Drying Recommended	no
Drying Temperature	100 °C
Drying Time, Dehumidified Dryer	3-4 h
Processing Moisture Content	≤0.2 %
Melt Temperature Optimum	205 °C
Min. melt temperature	205 °C
Max. melt temperature	210 °C
Screw tangential speed	≤0.3 m/s
Mold Temperature Optimum	105 °C
Min. mould temperature	90 °C
Max. mould temperature	120 °C
Hold pressure range	60 - 120 MPa
Back pressure	4 MPa
Ejection temperature	136 °C

Additional information

Injection molding

Preprocessing

Drying is generally not required because Celcon® and Hostaform® acetal copolymer materials are not hydroscopic nor are they degraded by moisture during processing. Excessive moisture can lead to splay (silver streaking) in molded parts. For better uniformity in molding especially when using regrind or material that has been stored in containers open to the atmosphere, recommended drying conditions are 80 c (180 F) for three hours. Desiccant hopper dryers are not required. Max. water content = 0.35%.

Processing

Standard reciprocating screw injection molding machines with a high compression screw (minimum 3:1 and preferably 4:1) and low back pressure (0.35 Mpa/50 PSI) are favored. Using a low compression screw (i.e.-general purpose with a 2:1 compression ratio) can result in unmelted particles and poor thermal homogeneity. Using a high back pressure to make up for a low compression ratio may lead to excessive shear heating and deterioration of the Celcon material.

Melt temperature: Preferred range 205-220 C (400-430 F) Melt temperature should never exceed 230 C (450 F).

Mold surface temperature: preferred range 93-121 C (200-250 F) especially with wall thickness less than 1.5 mm (0.060 in.). Wall thickness greater than 3 mm (1/8 in.) may use a cooler (82 C/180 F) mold surface temperature and wall thickness over 6 mm (1/4 in.) may use a cold mold surface temperature as low as 25 C (80 F). In general, mold surface temperatures lower than 82 C (180 F) may produce a hazy surface or a surface with flow lines, pits and other included defects.

Postprocessing

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Film extrusion

Postprocessing conditioning and moisturizing not required. It may be necessary to fixture large or complicated parts with varying wall thickness to prevent warpage while cooling to ambient temperature.

Preprocessing

Drying is generally not required because Celcon materials are not hydroscopic nor are they degraded by moisture during processing. Excessive moisture can cause surface defects on the extruded film. For better uniformity especially when using regrind or material that has been stored in containers open to the atmosphere, recommended drying conditions are 3 Hrs. at 80 C (180 F). Desiccant hopper dryers are not required. Max. moisture content = 0.35%.

Processing

Standard extruders with a length to diameter ratio of at least 20:1 are recommended. The screw should be a high compression ratio of at least 3:1 and preferably 4:1 to assure good melting and melt homogeneity. The design should be approximately 35% each for feed and metering sections with the remaining 30% as the transition zone.

Melt temperature: 160-220 C (320-430 F)

Postprocessing

Postprocessing conditioning or moisturizing is not required.

Profile extrusion Preprocessing

Drying is generally not required because Celcon materials are not hydroscopic nor are they degraded by moisture during processing. Excessive moisture can cause surface defects on the extrusion. For better uniformity especially when using regrind or material that has been stored in containers open to the atmosphere, recommended drying conditions are 3 Hrs. at 80 C (180 F). Desiccant hopper dryers are not required. Max. moisture content = 0.035%.

Processing

Standard extruders with a length to diameter ratio of at least 20:1 are recommended. The screw should be a high compression ratio of at least 3:1 and preferably 4:1 to assure good melting and melt homogeneity. The design should be approximately 35% each for feed and metering sections with the remaining 30% as the transition zone.

Melt temperature: 180-220 C (360-430 F).

Postprocessing

Postprocessing or moisturizing is not required. For thick walled extrusions (>3

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mm or 1/8 in.), annealing is recommended to reduce internal stresses.

Annealing temperature: 130-140 C (265-285 F) Annealing time: 10 min/mm thickness

	Annealing time. To min/min thickness
Blow molding	Preprocessing
	Consult product information services.
	Processing
	Consult product information services.
	Postprocessing
	Consult product information services.
Calandering	Preprocessing
	Consult product information services.
	Processing
	Consult product information services.
	Postprocessing
	Consult product information services.
Compression molding	Preprocessing
	Consult product information services.
	Processing
	Consult product information services.
	Postprocessing
	Consult product information services.
Processing Notes	Pre-Drying

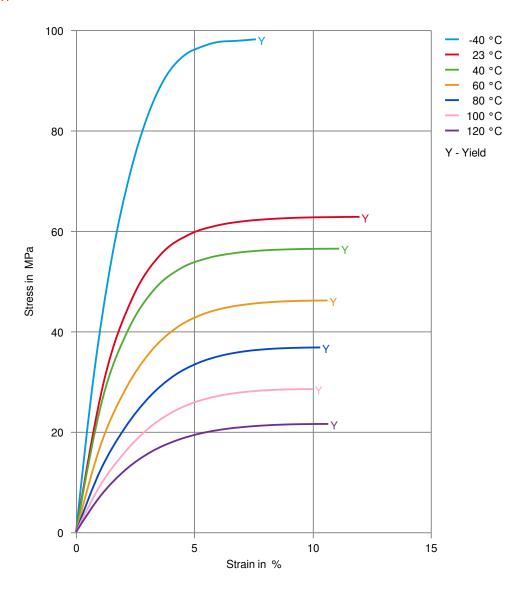
Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

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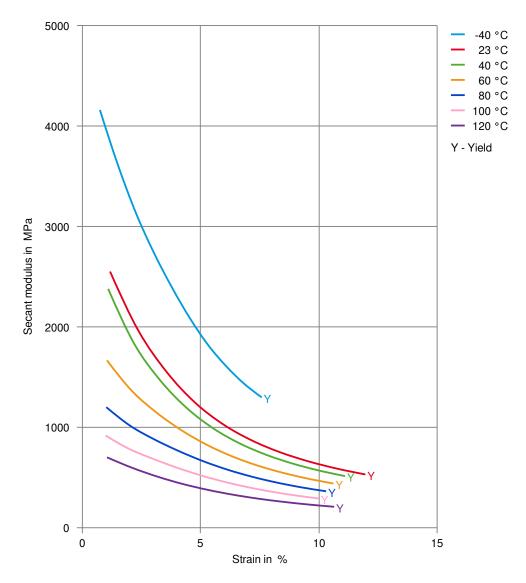
Stress-strain





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Secant modulus-strain



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